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BC846 series

65 V, 100 mA NPN general-purpose transistors

Rev. 9 — 25 September 2012 Product data sheet

1. Product profile

1.1 General description

NPN general-purpose transistors in Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number[1]	Package			PNP complement
	NXP	JEITA	JEDEC	
BC846	SOT23	-	TO-236AB	BC856
BC846W	SOT323	SC-70	-	BC856W
BC846T	SOT416	SC-75	-	BC856T

[1] Valid for all available selection groups.

1.2 Features and benefits

- General-purpose transistors
- SMD plastic packages
- Two different gain selections

1.3 Applications

- General-purpose switching and amplification

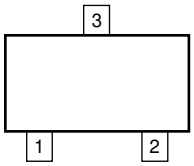
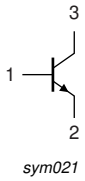
1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	65	V
I_C	collector current		-	-	100	mA
h_{FE}	DC current gain	V_{CE} = 5 V; I_C = 2 mA	110	-	450	
	h_{FE} group A		110	180	220	
	h_{FE} group B		200	290	450	

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
SOT23, SOT323, SOT416			
1	base		
2	emitter		
3	collector		

3. Ordering information

Table 4. Ordering information

Type number[1]	Package		
	Name	Description	Version
BC846	-	plastic surface-mounted package; 3 leads	SOT23
BC846W	SC-70	plastic surface-mounted package; 3 leads	SOT323
BC846T	SC-75	plastic surface-mounted package; 3 leads	SOT416

[1] Valid for all available selection groups.

4. Marking

Table 5. Marking codes

Type number	Marking code[1]
BC846	1D*
BC846A	1A*
BC846B	1B*
BC846W	1D*
BC846AW	1A*
BC846BW	1B*
BC846T	1M
BC846AT	1A
BC846BT	1B

[1] * = placeholder for manufacturing site code

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5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	80	V
V_{CEO}	collector-emitter voltage	open base		-	65	V
V_{EBO}	emitter-base voltage	open collector		-	6	V
I_C	collector current			-	100	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms		-	200	mA
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms		-	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]			
	SOT23			-	250	mW
	SOT323			-	200	mW
	SOT416			-	150	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			−65	+150	°C
T_{stg}	storage temperature			−65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]				
	SOT23			-	-	500	K/W
	SOT323			-	-	625	K/W
	SOT416			-	-	833	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

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7. Characteristics

Table 8. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	V_{CB} = 30 V; I_E = 0 A		-	-	15	nA
		V_{CB} = 30 V; I_E = 0 A; T_j = 150 °C		-	-	5	μA
I_{EBO}	emitter-base cut-off current	V_{EB} = 5 V; I_C = 0 A		-	-	100	nA
h_{FE}	DC current gain	V_{CE} = 5 V; I_C = 10 μA					
	h_{FE} group A			-	180	-	
	h_{FE} group B			-	290	-	
	DC current gain	V_{CE} = 5 V; I_C = 2 mA		110	-	450	
	h_{FE} group A			110	180	220	
	h_{FE} group B			200	290	450	
V_{CEsat}	collector-emitter saturation voltage	I_C = 10 mA; I_B = 0.5 mA		-	90	200	mV
		I_C = 100 mA; I_B = 5 mA	[1]	-	200	400	mV
V_{BEsat}	base-emitter saturation voltage	I_C = 10 mA; I_B = 0.5 mA	[2]	-	760	-	mV
		I_C = 100 mA; I_B = 5 mA	[2]	-	900	-	mV
V_{BE}	base-emitter voltage	I_C = 2 mA; V_{CE} = 5 V	[3]	580	660	700	mV
		I_C = 10 mA; V_{CE} = 5 V	[3]	-	-	770	mV
f_T	transition frequency	V_{CE} = 5 V; I_C = 10 mA; f = 100 MHz		100	-	-	MHz
C_c	collector capacitance	V_{CB} = 10 V; I_E = i_e = 0 A; f = 1 MHz		-	2	3	pF
C_e	emitter capacitance	V_{EB} = 0.5 V; I_C = i_c = 0 A; f = 1 MHz		-	11	-	pF
NF	noise figure	I_C = 200 μA; V_{CE} = 5 V; R_S = 2 kΩ; f = 1 kHz; B = 200 Hz		-	2	10	dB

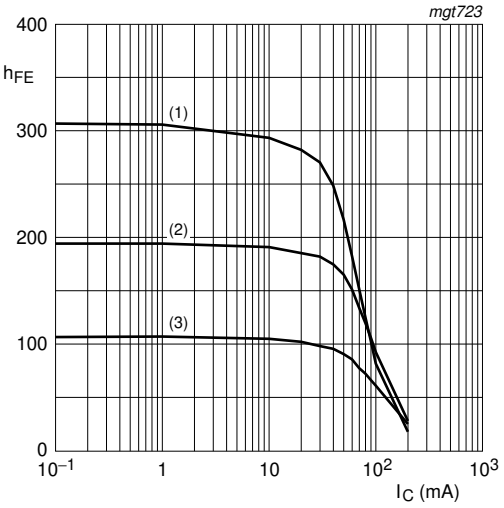
[1] Pulse test: $t_p \leq 300$ μs; $\delta = 0.02$.

[2] V_{BEsat} decreases by approximately 1.7 mV/K with increasing temperature.

[3] V_{BE} decreases by approximately 2 mV/K with increasing temperature.

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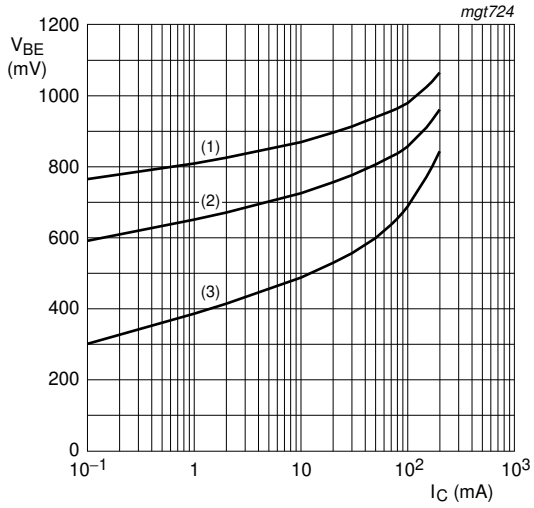
V_{CE} = 5 V

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 1. Selection A: DC current gain as a function of collector current; typical values



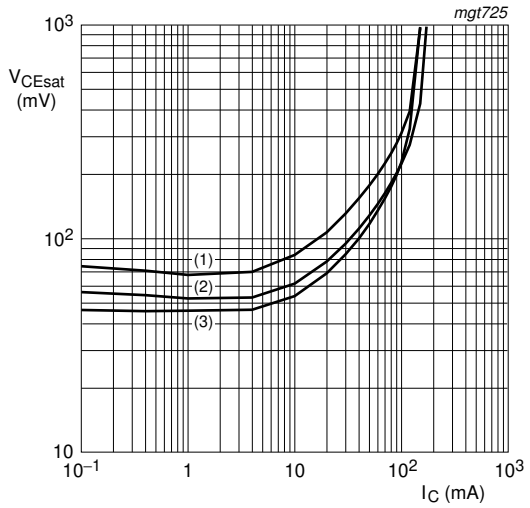
V_{CE} = 5 V

(1) T_{amb} = −55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 150 °C

Fig 2. Selection A: Base-emitter voltage as a function of collector current; typical values



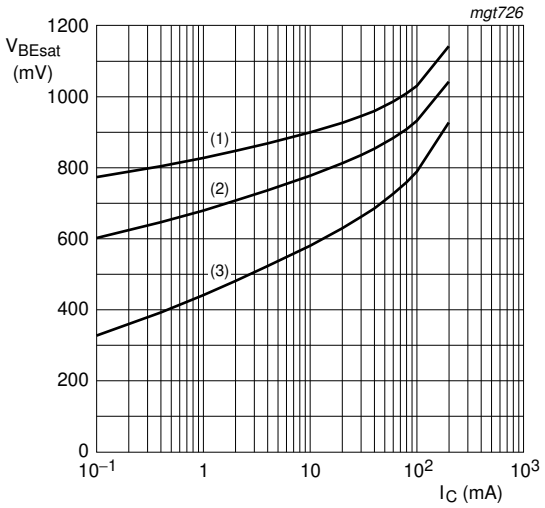
I_C/I_B = 20

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 3. Selection A: Collector-emitter saturation voltage as a function of collector current; typical values



I_C/I_B = 10

(1) T_{amb} = −55 °C

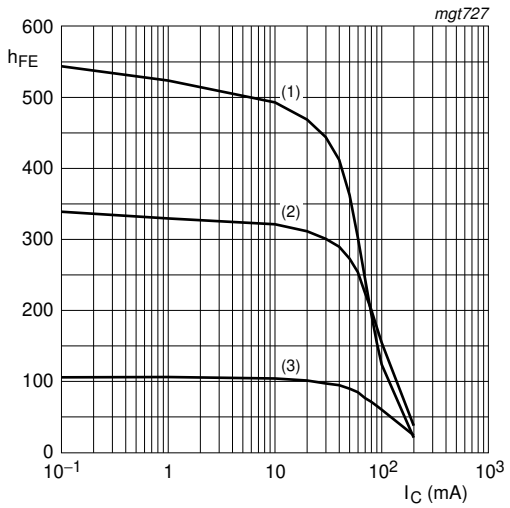
(2) T_{amb} = 25 °C

(3) T_{amb} = 150 °C

Fig 4. Selection A: Base-emitter saturation voltage as a function of collector current; typical values

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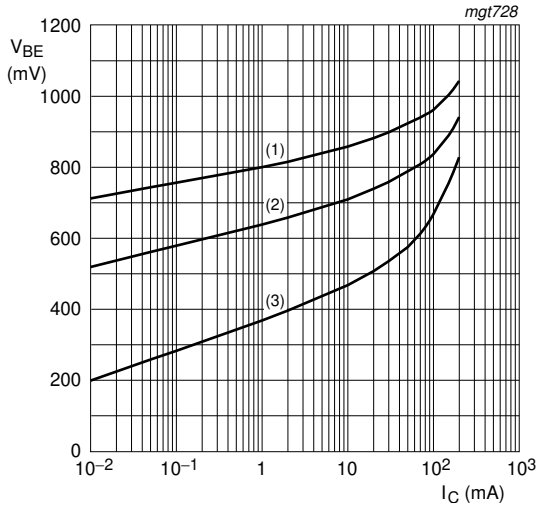
V_{CE} = 5 V

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 5. Selection B: DC current gain as a function of collector current; typical values



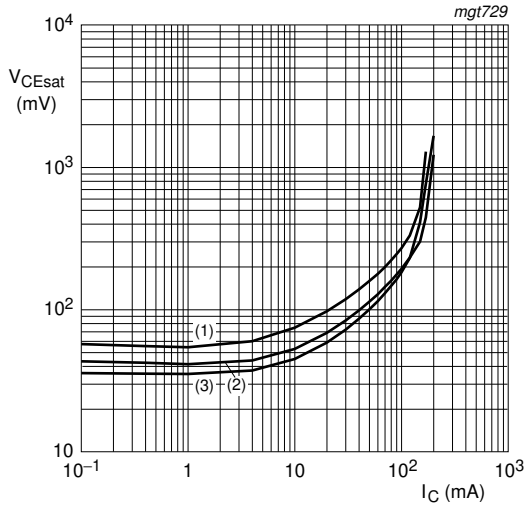
V_{CE} = 5 V

(1) T_{amb} = −55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 150 °C

Fig 6. Selection B: Base-emitter voltage as a function of collector current; typical values



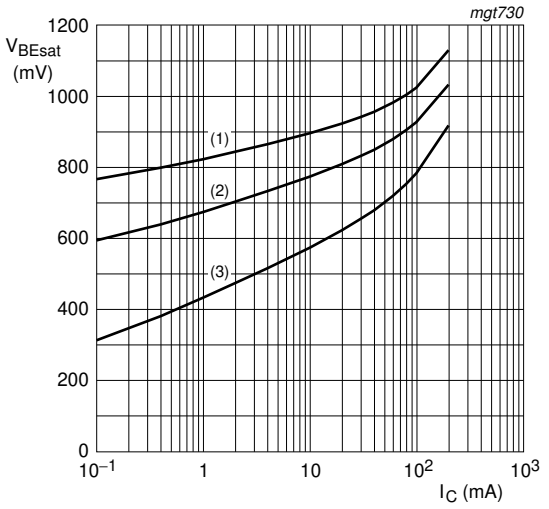
I_C/I_B = 20

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 7. Selection B: Collector-emitter saturation voltage as a function of collector current; typical values



I_C/I_B = 10

(1) T_{amb} = −55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 150 °C

Fig 8. Selection B: Base-emitter saturation voltage as a function of collector current; typical values

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8. Package outline

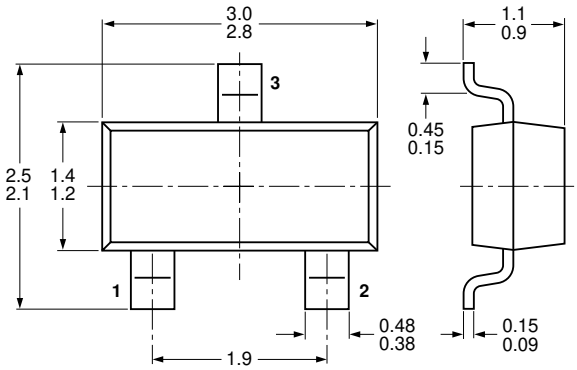


Fig 9. Package outline SOT23 (TO-236AB)

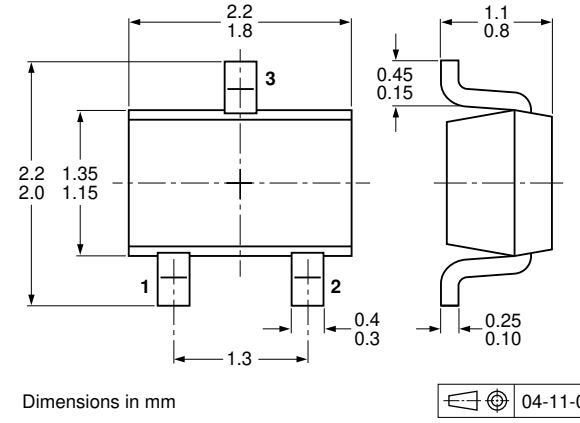


Fig 10. Package outline SOT323 (SC-70)

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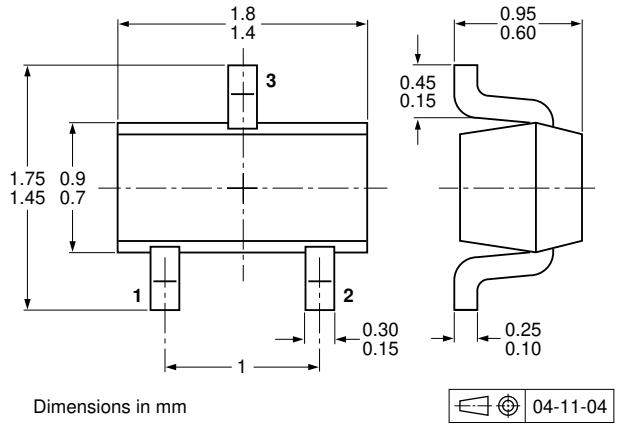


Fig 11. Package outline SOT416 (SC-75)

9. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number[2]	Package	Description	Packing quantity		
			1000	3000	4000
BC846	SOT23	4 mm pitch, 8 mm tape and reel	-215	-	-235
BC846W	SOT323	4 mm pitch, 8 mm tape and reel	-115	-	-135
BC846T	SOT416	4 mm pitch, 8 mm tape and reel	-115	-	-135

[1] For further information and the availability of packing methods, see Section 13.

[2] Valid for all available selection groups.

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10. Soldering

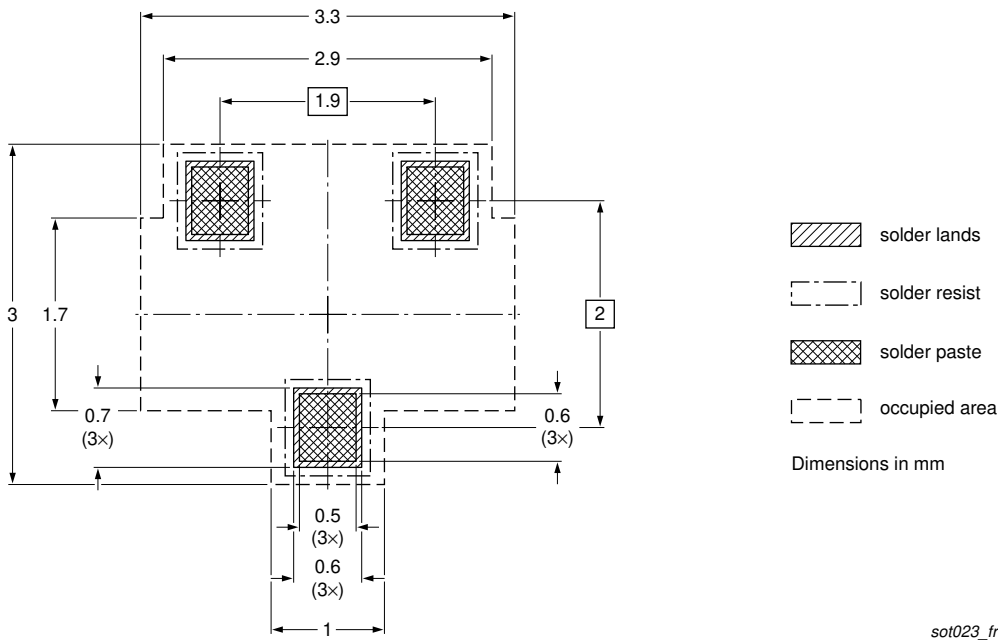


Fig 12. Reflow soldering footprint SOT23 (TO-236AB)

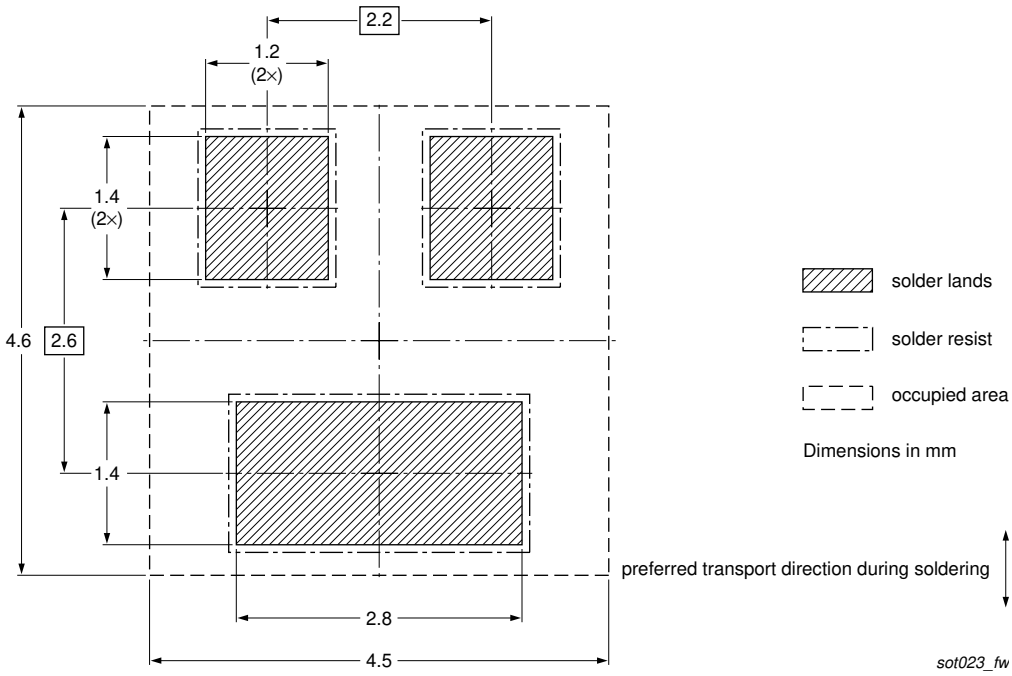


Fig 13. Wave soldering footprint SOT23 (TO-236AB)

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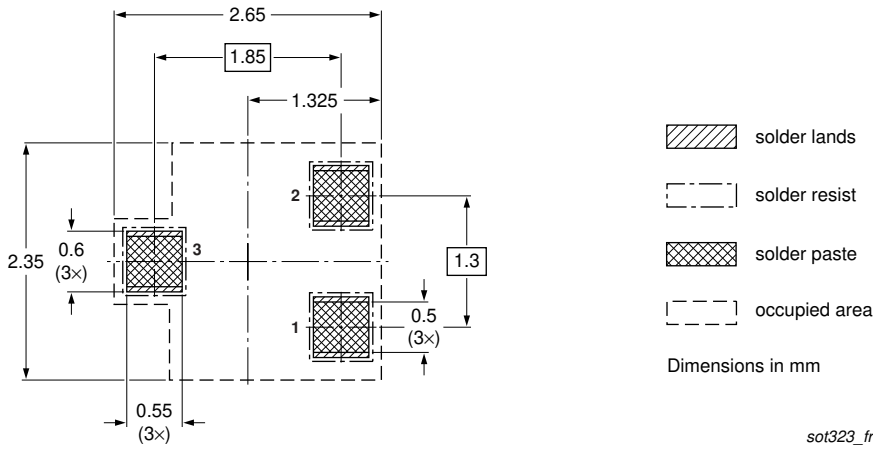


Fig 14. Reflow soldering footprint SOT323 (SC-70)

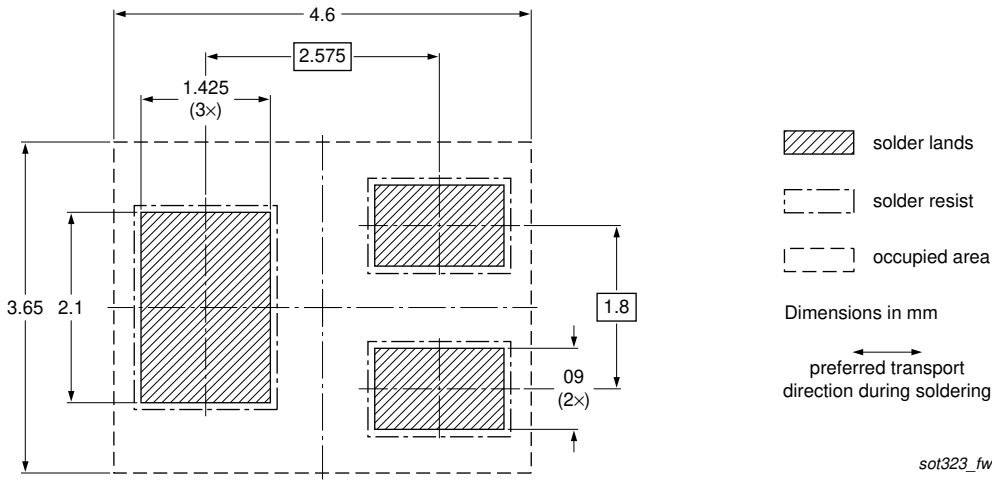


Fig 15. Wave soldering footprint SOT323 (SC-70)

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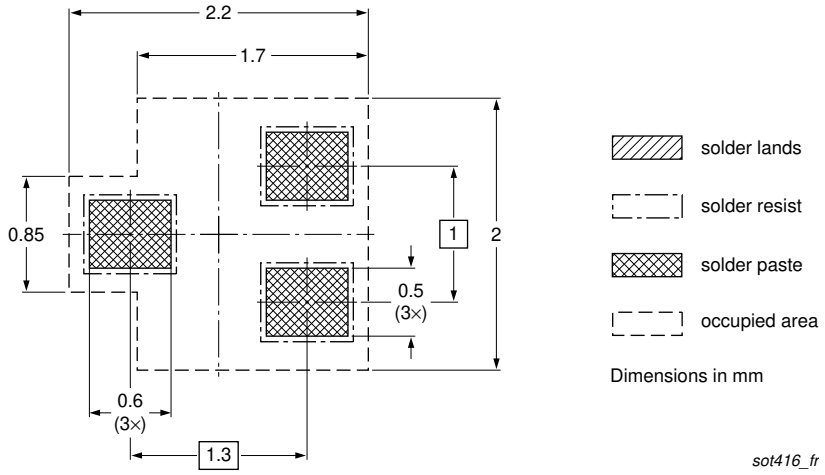


Fig 16. Reflow soldering footprint SOT416 (SC-75)

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11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC846_SER v.9	20120925	Product data sheet	-	BC846_SER v.8
Modifications:	• Table 6 “Limiting values”: P_{tot} values corrected			
BC846_SER v.8	20120424	Product data sheet		BC846_BC546_SER v.7
BC846_BC546_SER v.7	20091117	Product data sheet	-	BC846_BC546_SER v.6
BC846_BC546_SER v.6	20060207	Product data sheet	-	-

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12. Legal information

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 25 September 2012
Document identifier: BC846_SER